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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Philip A. Rochette PATENT APPLICATION  
Serial No.: 10/817,619 Group Art Unit: 2814  
Filed: April 1, 2004 Examiner: M. D. Pizarro-Crespo  
For: METHOD AND APPARATUS TO ELIMINATE GALVANIC  
CORROSION ON COPPER DOPED ALUMINUM BOND PADS  
ON INTEGRATED CIRCUITS

Response to Restriction Requirement

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

In response to the Restriction Requirement in the  
Office action mailed 06/01/2005 from the Patent and Trademark  
Office regarding the above-identified patent application,  
Applicant elects to prosecute the invention of Group I, claims  
1-5 and 14-18. Applicant withdraws the non-elected claims  
6-13.

CERTIFICATE OF MAILING

I hereby certify that this paper (along with any  
paper referred to as being attached or enclosed)  
is being deposited with the United States Postal  
Service on the date shown below with sufficient  
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addressed to: Commissioner for Patents, P.O. Box  
1450, Alexandria, Virginia 22313-1450.

Signed: Merle P. Garcia  
Typed Name: Merle P. Garcia  
Date: June 15, 2005

Respectfully submitted,

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